

LNPTTM THERMOCOMPTM COMPOUND JF003E

JF-1003 EM

DESCRIPTION

LNP THERMOCOMP JF003E compound is based on Polyethersulfone (PES) resin containing 15% glass fiber. Added features of this grade include: Easy Molding.

GENERAL INFORMATION	
Features	Good Processability, High stiffness/Strength, High temperature resistance, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polyethersulfone (PESU)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Building Component
Consumer	Sport/Leisure, Personal Accessory, Home Appliances, Commercial Appliance
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, break, 5 mm/min	101	MPa	ISO 527
Tensile Strain, break, 5 mm/min	2.3	%	ISO 527
Tensile Modulus, 1 mm/min	5660	MPa	ISO 527
Flexural Stress	174	MPa	ISO 178
Flexural Modulus, 2 mm/min	5330	MPa	ISO 178
Tensile Stress, brk, Type I, 5 mm/min	107	MPa	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	2.8	%	ASTM D638
Tensile Modulus, 5 mm/min	5660	MPa	ASTM D638
Flexural Strength, 1.3 mm/min, 50 mm span	174	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	5680	MPa	ASTM D790
IMPACT ⁽¹⁾			
Izod Impact, notched 80*10*4 +23°C	5	kJ/m ²	ISO 180/1A
Izod Impact, unnotched 80*10*4 +23°C	33	kJ/m ²	ISO 180/1U
Multiaxial Impact	1	J	ISO 6603
Izod Impact, notched, 23°C	43	J/m	ASTM D256
Izod Impact, unnotched, 23°C	500	J/m	ASTM D4812
Instrumented Dart Impact Total Energy, 23°C	7	J	ASTM D3763
THERMAL ⁽¹⁾			
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	218	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	211	°C	ISO 75/Af

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
HDT, 0.45 MPa, 3.2 mm, unannealed	218	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	210	°C	ASTM D648
CTE, -30°C to 30°C, flow	4.2E-05	1 / °C	ASTM D696
CTE, -30°C to 30°C, xflow	4.7E-05	1 / °C	ASTM D696
PHYSICAL ⁽¹⁾			
Moisture Absorption (23°C / 50% RH)	0.9	%	ISO 62
Specific Gravity	1.49	-	ASTM D792
Density	1.48	g/cm ³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.45	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.4 – 0.6	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.6 – 0.8	%	ASTM D955
INJECTION MOLDING ⁽³⁾			
Drying Temperature	120 – 150	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.05	%	
Melt Temperature	355 – 370	°C	
Front - Zone 3 Temperature	370 – 380	°C	
Middle - Zone 2 Temperature	360 – 370	°C	
Rear - Zone 1 Temperature	345 – 355	°C	
Mold Temperature	140 – 150	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	60 – 100	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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